

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously presented) A structure comprising:
a frame; and
a mold having at least one air vent from which the resin can seep out of during the injecting phase into said mold, said air vent being positioned between an upper and a lower surface of said frame, wherein said frame includes: a through hole placed adjacent to an outlet of said air vent so that when the resin has solidified it forms a flash which is in coherence with one of the upper and lower surfaces of said frame.
2. (Previously presented) The structure according to claim 1 wherein said through hole has an ellipsoidal section having its center positioned on the axis of said air vent and has the minor diameter dimension of said hole shorter than the diameter of said air vent.
3. (Previously presented) The structure according to claim 1 wherein said through hole has a circular section with its center positioned on the axis of said air vent and has the dimension of its diameter equal to or shorter than that of said air vent.
4. (Currently Amended) The structure according to claim 2 wherein said air vent, in combination with said hole having an ellipsoidal section, gives rise to a flash of resin on the upper surface of said frame and to a flash of resin on the lower surface of said frame, with an overall combined thickness equal to or exceeding 1 mm.
5. (Previously presented) The structure according to claim 2 wherein said hole with ellipsoidal section is positioned at a distance of more than 1 mm from said air vent.

6. (Previously presented) The structure according to claim 3 wherein said air vent by means of said hole of circular section gives rise to a flash only on the upper surface of said frame, the flash having a thickness ranging between 20-25 μm .

7. (Previously presented) The structure according to claim 3 wherein said hole of circular section is positioned at a distance of more than 1 mm from said air vent.

8. (Previously presented) An integrated circuit package, comprising:
a semiconductor device;
a molded portion formed around the semiconductor device and having a flashing portion of molded material extruded from the molded portion at a peripheral area thereof; and
a lead-frame external to the molded portion and having a hole adjacent to the peripheral area of the molded portion having the flashing portion extruded therefrom, the flashing portion at least partially filling the hole.

9. (Previously presented) The integrated circuit package of claim 8 wherein the hole is formed on an axis passing through the flashing portion.

10. (Previously presented) The integrated circuit package of claim 9 wherein the hole is a through-hole extending completely through the lead-frame.

11. (Currently Amended) The integrated circuit package of claim 10 wherein the flashing portion at least partially filling the hole includes a first portion formed on a first surface of the lead-frame ~~facing away from the molded portion~~ and a second portion formed on a second surface of the lead-frame ~~facing toward the molded portion~~.

12. (Previously presented) The integrated circuit package of claim 9 wherein the hole is a recess formed in the lead-frame

13. (Previously presented) The integrated circuit package of claim 9 wherein the hole is substantially round in shape.

14. (Previously presented) The integrated circuit package of claim 9 wherein the hole is substantially elliptical in shape.

15. (Previously presented) The integrated circuit package of claim 14 wherein the hole is spaced a predetermined distance away from the extrusion of the flashing portion from the molded portion.

16. (Previously presented) A semiconductor lead-frame for an integrated circuit having a molded portion formed thereover, the molded portion having one or more flashing portions formed at peripheral extrusion areas thereof, the lead-frame comprising:

a conductive skeleton having a support surface and a plurality of conductive strips on the surface, the conductive strips defining an air vent zone of the surface that is structured for placement adjacent to one of the peripheral extrusion areas, the air vent zone including a hole in the surface for receiving a portion of one of the flashing portions.

17. (Previously presented) The lead-frame of claim 16 wherein the hole is a recess formed in a surface of the conductive strip facing away from the molded portion.

18. (Previously presented) The lead-frame of claim 16 wherein the hole is aligned with the flashing portion.

19. (Previously presented) The lead-frame of claim 16 wherein the hole is a passage through the conductive strip.

20. (Previously presented) The lead-frame of claim 19 wherein the hole is substantially circular in shape.

21. (Previously presented) The lead-frame of claim 19 wherein the hole is substantially ellipsoidal in shape.

22. (Previously presented) The lead-frame of claim 16 wherein the hole is spaced a predetermined distance away from an air vent of the air vent zone.

23. (Previously presented) The lead-frame of claim 16, further comprising:
a semiconductor device mounted on the support surface of the conductive skeleton; wherein the molded portion is formed over the semiconductor device, the one or more flashing portions extending into the hole.

24. (Previously presented) The lead-frame of claim 23 wherein the one or more flashing portions extend across a surface of the conductive strip facing away from the molded portion.

25. (Previously presented) The lead-frame of claim 24 wherein:
the hole is a passage through the conductive strip; and
the one or more flashing portions extend through the passage.

26. (Previously presented) The lead-frame of claim 25 wherein the one or more flashing portions include a button portion on a surface of the conductive strip facing away from the molded portion.